

Surface Mount Zener Diodes

FEATURES

• Zener voltage range selection: 2.4V to 39V

• Ideally suited for automated assembly processes

• Moisture sensitivity: Level 1 per J-STD-020

RoHS Compliant

• Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Low voltage stabilzers or voltage references
- Adapters
- Lighting application
- On-board DC/DC converter

MECHANICAL DATA

• Case: SOT-23

 Molding compound: UL flammability classification rating 94V-0

• Terminal: Matte tin plated leads, solderable per J-STD-002

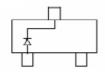
Meet JESD 201 class 1A whisker test

Weight: 8mg (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	TINU		
V _Z	2.4-39	V		
P_{D}	300	mW		
V _F at I _F =10mA	0.9	V		
T _J Max.	150	°C		
Package	SOT-23			
Configuration	Single die			







ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)					
PARAMETER	SYMBOL	VALUE	UNIT		
Power dissipation	P _D	300	mW		
Forward voltage @ I _F =10mA	V_{F}	0.9	V		
Junction temperature range	T_J	-65 to +150	°C		
Storage temperature range	T _{STG}	-65 to +150	°C		

THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	417	°C/W		

1



PART	MARKING	ZENER VOLTAGE RANGE (Note 2)			ZENER IMPEDANCE (Note 3)		LEAKAGE CURRENT		TYPICAL TEMPERATURE COEFFICIENT			
NUMBER	CODE		V _z @ I _z	т	I _{ZT}	Z _{ZT} @ I _{ZT}	Z _{ZK} @ I _{ZK}	I _{ZK}	I _z @) V ₇		I _{ZT}
(Note 1)	0022	V V			mA	Ω	Ω	mA	μA	V		//°C
		Nom.	Min.	Max.		Max.	Max.		Max.		Min.	Max.
BZX84C2V4	Z11	2.4	2.2	2.6	5	100	600	1.0	50	1.0	-3.5	0
BZX84C2V7	Z12	2.7	2.5	2.9	5	100	600	1.0	20	1.0	-3.5	0
BZX84C3V0	Z13	3.0	2.8	3.2	5	95	600	1.0	10	1.0	-3.5	0
BZX84C3V3	Z14	3.3	3.1	3.5	5	95	600	1.0	5.0	1.0	-3.5	0
BZX84C3V6	Z15	3.6	3.4	3.8	5	90	600	1.0	5.0	1.0	-3.5	0
BZX84C3V9	Z16	3.9	3.7	4.1	5	90	600	1.0	3.0	1.0	-3.5	0
BZX84C4V3	Z17	4.3	4.0	4.6	5	90	600	1.0	3.0	1.0	-3.5	0.0
BZX84C4V7	Z1	4.7	4.4	5.0	5	80	500	1.0	3.0	2.0	-3.5	0.2
BZX84C5V1	Z2	5.1	4.8	5.4	5	60	480	1.0	2.0	2.0	-2.7	1.2
BZX84C5V6	Z3	5.6	5.2	6.0	5	40	400	1.0	1.0	2.0	-2.0	2.5
BZX84C6V2	Z4	6.2	5.8	6.6	5	10	150	1.0	3.0	4.0	0.4	3.7
BZX84C6V8	Z5	6.8	6.4	7.2	5	15	80	1.0	2.0	4.0	1.2	4.5
BZX84C7V5	Z6	7.5	7.0	7.9	5	15	80	1.0	1.0	5.0	2.5	5.3
BZX84C8V2	Z7	8.2	7.7	8.7	5	15	80	1.0	0.7	5.0	3.2	6.1
BZX84C9V1	Z8	9.1	8.5	9.6	5	15	100	1.0	0.5	6.0	3.8	7.0
BZX84C10	Z9	10	9.4	10.6	5	20	150	1.0	0.2	7.0	4.5	8.0
BZX84C11	Y1.	11	10.4	11.6	5	20	150	1.0	0.1	8.0	5.4	9.0
BZX84C12	Y2.	12	11.4	12.7	5	25	150	1.0	0.1	8.0	6.0	10.0
BZX84C13	Y3	13	12.4	14.1	5	30	170	1.0	0.1	8.0	7.0	11.0
BZX84C15	Y4	15	13.8	15.6	5	30	200	1.0	0.1	10.5	9.2	13.0
BZX84C16	Y5	16	15.3	17.1	5	40	200	1.0	0.1	11.2	10.4	14.0
BZX84C18	Y6	18	16.8	19.1	5	45	225	1.0	0.1	12.6	12.4	16.0
BZX84C20	Y7	20	18.8	21.2	5	55	225	1.0	0.1	14.0	14.4	18.0
BZX84C22	Y8	22	20.8	23.3	5	55	250	1.0	0.1	15.4	16.4	20.0
BZX84C24	Y9	24	22.8	25.6	5	70	250	1.0	0.1	16.8	18.4	22.0
BZX84C27	Y10	27	25.1	28.9	2	80	300	0.5	0.1	18.9	21.4	25.3
BZX84C30	Y11	30	28	32	2	80	300	0.5	0.1	21.0	24.4	29.4
BZX84C33	Y12	33	31	35	2	80	325	0.5	0.1	23.1	27.4	33.4
BZX84C36	Y13	36	34	38	2	90	350	0.5	0.1	25.2	30.4	37.4
BZX84C39	Y14	39	37	41	2	130	350	0.5	0.1	27.3	33.4	41.2

Notes

- 1. Valid provided that device terminals are kept at ambient temerature.
- 2. Tested with pulses, 300µs pulse width, period = 5 ms
- 3. f = 1KHz



Taiwan Semiconductor

ORDERING INFORMATION					
ORDERING CODE (Note 1, 2)	PACKAGE	PACKING			
BZX84Cxxx RF	SOT-23	3K / 7" Reel			
BZX84Cxxx RFG	SOT-23	3K / 7" Reel			

Note 1:

Note 2:

[&]quot;xxx" defines voltage from 2.4V (BZX84C2V4) to 39V (BZX84C39)

[&]quot;G" means green compound (halogen free)



Taiwan Semiconductor

CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig. 1 Power Derating Curve

500

400

300

200

0

100

T_A, Ambient Temperature (°C)

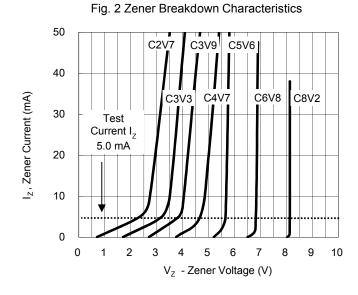
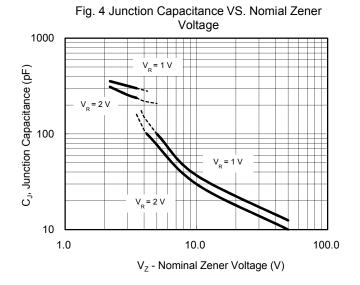


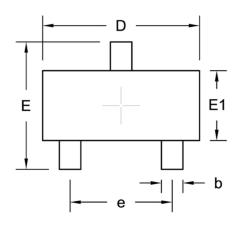
Fig. 3 Zener Breakdown Characteristics 30 C10 Test Current I_z C12 2 mA C15 I₂, Zener Current (mA) C18 C22 C27 Test Current I₇ C33 C36 5 mA 10 C39 0 0 10 20 30 40 V_z - Zener Voltage (V)

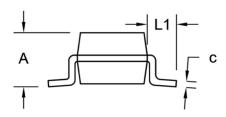




PACKAGE OUTLINE DIMENSION

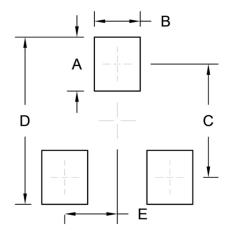
SOT-23





DIM.	Unit (mm)		Unit ((inch)
DIIVI.	Min.	Max.	Min.	Max.
Α	0.89	1.12	0.035	0.044
b	0.30	0.50	0.012	0.020
С	0.08	0.20	0.003	0.008
D	2.80	3.04	0.110	0.120
E	2.10	2.64	0.083	0.104
E1	1.20	1.40	0.047	0.055
е	1.90 BSC		0.07	5 BSC
L1	0.54 REF.		0.02	I REF.

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
А	1.00	0.039
В	0.85	0.033
С	2.10	0.083
D	3.10	0.122
E	0.98	0.039



Taiwan Semiconductor

Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.